

ABSTRACT

CLAMP CALIBRATION APPARATUS AND METHOD

5

The invention provides an apparatus and method to calibrate a clamp, such as a wire clamp, which is suitable for use with a wire-bonding machine for semiconductor devices. A contact means is arranged to be contacted by an arm of the clamping device and a sensing mechanism is positioned in
10 operational relationship with the arm. An indexing means is adapted to change positions of the clamping device relative to the contact means incrementally as said arm maintains contact with the contact means. The sensing mechanism is capable of sensing feedback from said arm at various positions of the clamping device relative to the contact means. The apparatus
15 is particularly suitable for measuring a clamping force and/or a clamping gap between clamping arms of the clamping device.

(Fig. 4)